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Improving luminescence response in ZnGeN₂/GaN superlattices: defect reduction through composition control

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Abstract

Color-mixed (cm) light-emitting diodes (LEDs) are theoretically the most efficient white light emitters, projected to improve white light luminous efficacy by 34% compared to incumbent phosphor converted LEDs. Since white light technology is pervasive and essential, small improvements in LED technology can result in energy savings. However, cm-LEDs are not yet realized due to poor efficacy in green and amber emitting materials, a spectral region colloquially referred to as the Green Gap. ZnGeN₂ is nearly isostructural and closely lattice-matched to GaN and can be heteroepitaxially integrated with existing GaN devices; ZnGeN₂/GaN hybrid structures are theorized to emit green (~530 nm) light with a spontaneous emission rate 4.6–4.9 times higher than traditional InGaN LEDs when incorporated into III-N LED structures. In this report we demonstrate the molecular beam epitaxy (MBE) growth of GaN and ZnGeN₂ superlattices, an important step towards realizing multiple quantum well structures required for efficient LEDs. Elemental analysis, including atom probe tomography, shows that Ga and Ge are observed in both ZnGeN₂ and GaN layers, degrading the structural uniformity. The lack of elemental abruptness also leads to increased defect luminescence and reabsorption of band edge luminescence. The source of unintentional Ga distributed throughout the ZnGeN₂ layers was identified as excess flux escaping from around the closed MBE shutter. The source of unintentional Ge, which tended to incorporate as a single delta-doped layer in GaN, was identified as Ge riding along the cyclical metal-rich Ga adlayer used for high quality GaN, incorporating during subsequent nitrogen-rich growth step. Modifying the growth strategy results in improved structural quality, elemental abruptness, and luminescence response. This realization of structurally and elementally abrupt interfaces demonstrates the potential of heteroepitaxially integrated binary and ternary nitrides for energy-relevant devices.

Supplementary material for this article is available [online](#)

Keywords: ZnGeN₂, GaN, EDS, APT, PL, superlattice, MBE

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1. Introduction

Color-mixed (cm) light-emitting diode (LED) technologies are projected to increase luminous efficacy (lm/W) by 34% when compared to traditional phosphor-converted (pc) LEDs according to a 2050 U.S. Department of Energy target [1]. However, pc-LEDs are the industry standard for white light because it is currently more efficient to down-convert low In-content blue LEDs than it is to use direct-emitting green and amber LEDs with higher In content. This down conversion process is inherently lossy- energy is dissipated to heat to convert to the longer wavelengths of light. cm-LEDs, which use individual emitters for blue, green, red, and amber light, are theoretically the most efficient method for generating white light. These cm-LEDs have not yet been realized due to the Green Gap, a spectral region from 500-600 nm with significantly lower demonstrated efficiency than blue III-N or red III-V LEDs [1]. The Green Gap results from fundamental materials limitations in the (In,Ga)N system, including alloy immiscibility and the large polarization and lattice mismatch between the two binary compounds [2–4].

One solution to improve green or amber LED efficiency in nitride semiconductors is an alternative emitter material with an appropriate bandgap and a more favorable lattice match to GaN when compared to InGaN alloys. One proposed material is the heterovalent ternary ZnGeN₂, which is nearly lattice-matched to GaN (~0.2% lattice mismatch) [5]. ZnGeN₂ is theorized to have a bandgap tunable with disorder or band engineering into the green and amber regions, with a spontaneous emission rate 4.6–4.9 times higher than traditional InGaN LEDs when incorporated into current III-N LED structures [6–10]. Cation-ordered ZnGeN₂ is theorized to have a type-II band offset with GaN, although small amounts of cation disorder are theorized to decrease the band gap enough to result in a type-I band offset [8]. ZnGeN₂ epitaxy has already been demonstrated by metal-organic chemical vapor deposition (MOCVD) [11–18], sputtering [7, 19], and molecular beam epitaxy (MBE) [5, 20, 21]. Heterostructures of ZnGeN₂ and GaN have been demonstrated by MBE and MOCVD, and heterostructures with GaN and InGaN have been demonstrated by MOCVD, although indium was observed to diffuse broadly across the entire heterostructure [15, 21]. To achieve highly efficient LEDs, superlattices (multiple quantum well structures) with abrupt interfaces are required but have not been demonstrated in the III-N/II-IV-N₂ material system.

This study investigates ZnGeN₂/GaN superlattices to explore the effects of multiple heterointerfaces on structure, compositional purity, and interfacial abruptness. We demonstrate growth of five repeating unit superlattices of ZnGeN₂ and GaN on commercial GaN templates. We observe unintentional incorporation of Ge in GaN and Ga in ZnGeN₂, and present growth strategies to reduce unintentional impurities in each layer. Spatially resolved composition is correlated with structural uniformity which is observed to impact the luminescence response of the superlattice. Improving the compositional abruptness results in improved structural uniformity,

decreased defect luminescence, and brighter band edge luminescence due to reduced parasitic absorption.

2. Experimental section

GaN and ZnGeN₂ were grown by MBE on n-type GaN templates (3L Corp, Si-doped, 6 μm thick), using previously published methods [21]. The substrates were cleaned *in situ* by three Ga polishing cycles, used to remove the surface oxide. In this process the GaN surface is covered with Ga and then heated to form and desorb Ga₂O along with excess Ga [22]. Two samples were investigated, each targeting five repeating units of 2.6 nm ZnGeN₂/13 nm GaN. Metal-modulated epitaxy (MME) was used to grow GaN with a III/V ratio of 1.8, 10/10 s Ga shutter open/closed times, and a substrate temperature of 600 °C [23]. Three MME cycles were required to deposit the 13 nm GaN layers. ZnGeN₂ was grown in a nitrogen-rich adsorption-controlled regime with a Zn overpressure and a substrate temperature of 400°C. The substrate temperature was calibrated to the melting point of Al using a pyrometer. Each growth followed the same structure: a 130 nm GaN regrowth was deposited on the Ga-polished n-GaN template, followed by five repeating superlattice units, and capped with 130 nm GaN (see figure 1).

X-ray diffraction (XRD) and reflection high-energy electron diffraction (RHEED) were used to investigate structural quality. *In situ* RHEED was performed using a 20 keV Staib Instruments electron gun and a CCD camera/phosphor screen. Symmetric XRD was performed in a triple-axis geometry using a SmartLab Rigaku XRD with an incident beam Ge(220) 2-bounce monochromator and diffracted beam Ge(220)×2 analyzer crystal. Reciprocal space maps (RSMs) were taken using a Panalytical MRD-Pro sourcing Cu-Kα radiation with a parabolic mirror and Ge (400) 4-bounce monochromator. The two-dimensional CCD detector has a 2θ resolution of 0.0025°.

Photoluminescence (PL) was used to investigate optical properties at low temperature (4 K). A 325 nm He–Cd laser was used for excitation filtered to 1 mW incident power. Data was collected with a 0.3 m spectrometer and Si-CCD detector with a UV sensitive coating. A white-light standard (from the National Institute of Standards and Technology) was used to correct for wavelength-dependent detector efficiency.

Specimens for atom probe tomography (APT) and transmission electron microscopy (TEM) were prepared using lift-out focused ion beam (FIB) methods on a Tescan S8252G FIB/scanning electron microscope instrument [24, 25]. TEM and scanning TEM (STEM) imaging were performed on a Thermo Fisher Scientific Talos F200X instrument using a 200 keV accelerating voltage. Scanning transmission energy dispersive x-ray spectroscopy (STEM-EDS) maps were collected at various regions around the layered structure and processed using Bruker's Esprit 1.9 software. APT specimens were prepared such that they could also be imaged in the TEM before and after APT analysis [26]. APT data were collected via laser pulsing on a Cameca LEAP 4000X Si instrument at

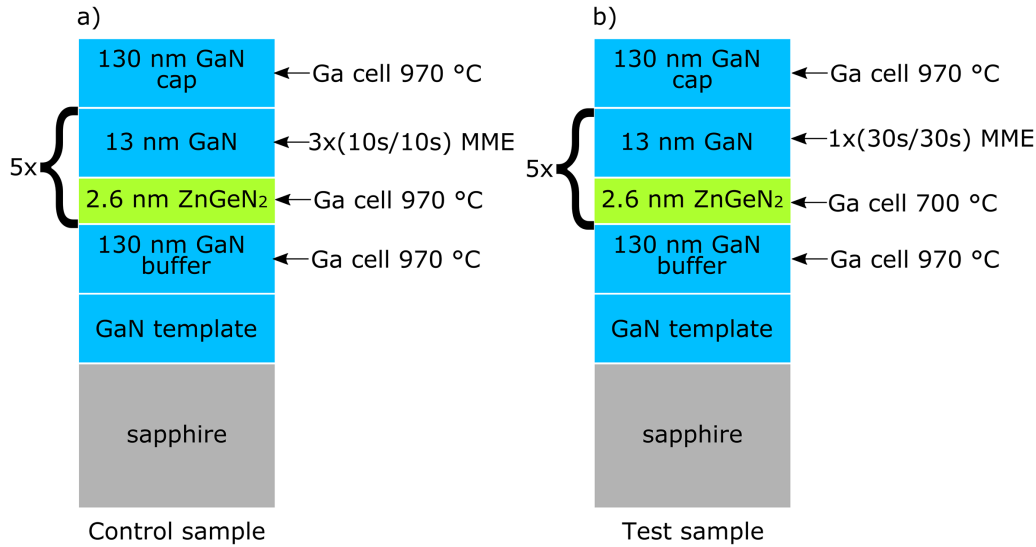


Figure 1. Control sample (a) and test sample (b) used to identify sources of unintentional Ga incorporation into ZnGeN₂ and Ge incorporation into GaN. They have identical structures with noted growth parameters modified during superlattice growth. The superlattice region is indicated by curly brackets. The test sample decreases the idle shuttered Ga temperature during ZnGeN₂ growth and utilizes a single longer MME cycle (30 s shutter open/30 s shutter closed), while the control sample does not change the Ga temperature and uses three shorter MME cycles (10 s shutter open/10 s shutter closed).

a base temperature of 51.4 K and flight path length of 90 mm. The laser pulse energies ranged from 9 to 90 fJ with pulse repetition rates of either 625 or 833 kHz. APT reconstructions were generated and analyzed in Cameca's IVAS 3.6.18 software. The TEM images (SI figure 1) were used to inform the reconstruction parameters following the method of Diercks and Gorman [27].

3. Results

Due to the disparate growth temperatures for ZnGeN₂ (400 °C) and GaN (600 °C) synthesis by MBE growth was interrupted between layers for a temperature ramp with all shutters closed, i.e. no direct nitrogen flux. ZnGeN₂ synthesis was initiated as soon as the substrate temperature reached 400 °C. To avoid decomposition of the ZnGeN₂, the GaN layer was deposited upon temperature ramping, opening the shutters at 475 °C and continuing to ramp at 200 °C/min to 600 °C. Typically the first 6 nm – 7 nm of the GaN layer were deposited during the temperature ramp, with the remaining thickness grown at 600 °C. The control sample (figure 1(a)) was grown with Ga at the GaN growth temperature (~970 °C) with a closed shutter during ZnGeN₂ growth layer. The test sample (figure 1(b)) was grown with the Ga cell cooled to 700 °C degrees and a closed shutter during ZnGeN₂ layer growth. The Ga cell was cooled during ZnGeN₂ growth to investigate the source of unintentional Ga in ZnGeN₂ layers. The GaN superlattice layer for the test sample was grown using a single MME cycle of identical thickness (30 s shutter open/30 s shutter closed), compared to three MME cycles (10 s shutter open/10 s shutter closed) for the control sample, to investigate Ge incorporation in the GaN layers. Metal rich growth of GaN

on ZnGeN₂ is important to prevent 3D island growth due to the unfavorable surface energy configuration since ZnGeN₂ grows in a 2D layer-by-layer growth mode when nucleated on GaN (as seen by RHEED oscillations). In other words ZnGeN₂ can wet the GaN surface, but GaN will not wet the ZnGeN₂ surface without the presence of a metallic Ga adlayer [28].

The surface quality and crystallinity of each sample were monitored by RHEED. RHEED patterns for the first and last ZnGeN₂ superlattice layers, taken at the end of each layer growth, are shown in figure 2(b). RHEED oscillations, indicative of 2D layer by layer growth, were used to monitor the ZnGeN₂ layer thickness (figure 2(a)). The RHEED pattern of the GaN buffer prior to growth shows strong Kikuchi lines from inelastic bulk scattering that diminish in intensity at the end of growth. A (2×2) surface reconstruction is observed indicative of a flat Ga-polar surface. We observe streaky RHEED patterns throughout the growth of all layers, indicative of a flat surface (complete set of RHEED images available in SI figure 2). However, the diffraction intensity tends to decrease during each ZnGeN₂ layer, consistent with increasing disorder. The intensity is regained upon each GaN layer growth, and (2×2) reconstructions were instantaneously visible for each GaN layer. There were no significant changes observed by RHEED when comparing the test sample to the control sample.

Symmetric XRD around the (0002) peak is shown in figure 3(a). The control sample shows weak 1st order superlattice reflections with a superlattice period of approximately 13.5 nm. The test sample shows up to 3rd order superlattice peaks with a superlattice period of 15 nm. The set of Pendellösung fringes with highest frequency is associated with the GaN cap (130 nm) in each XRD pattern. RSMs around the (1 0 $\bar{1}$ 5) reflection, shown in figures 3(b) and (c), were

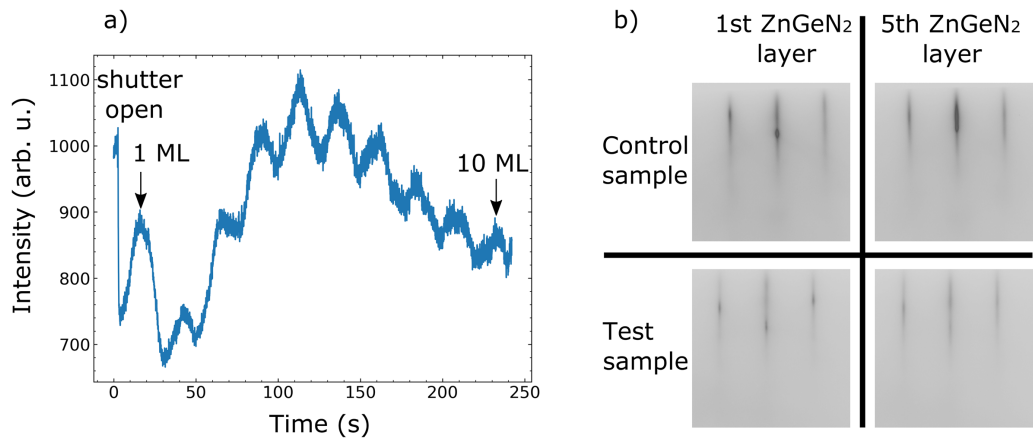


Figure 2. Reflection high-energy electron diffraction (RHEED) of the control and test samples showing layer by layer growth and smooth surfaces. (a) RHEED intensity (arbitrary units) versus time (s) for the duration of the first ZnGeN₂ layer in the test sample. Each oscillation shows the completion of one monolayer (2.6 Å) of ZnGeN₂. (b) RHEED images for the 1st and last ZnGeN₂ layers for both the control and test samples.

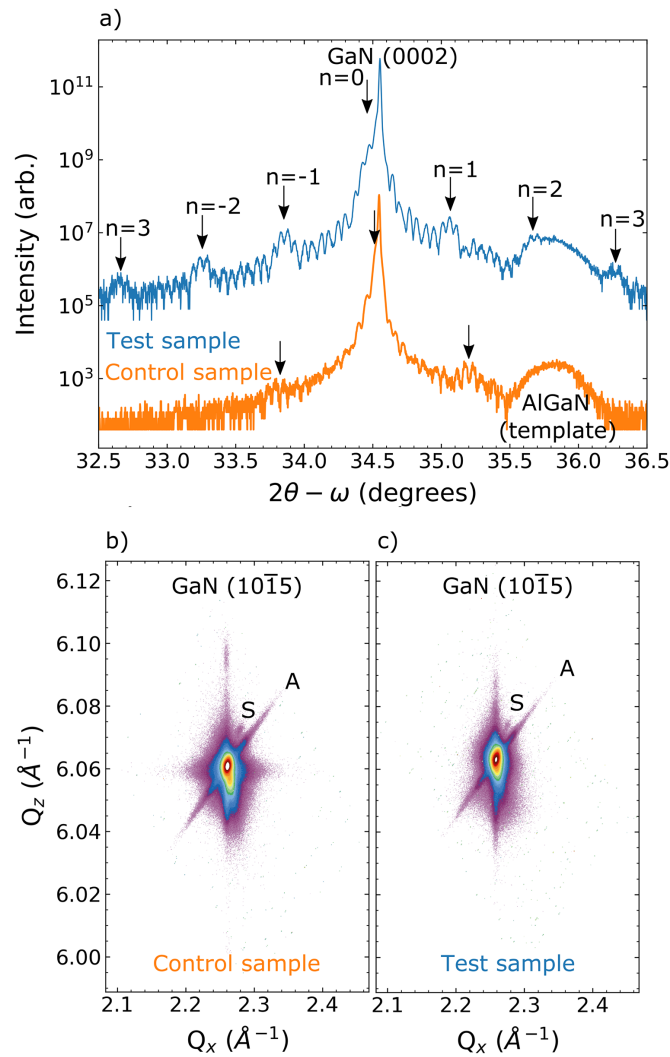


Figure 3. XRD structural characterization of the control and test structures. (a) Symmetric XRD of the control sample (orange) and test sample (blue). Asymmetric reciprocal space maps (RSM) around the (1 0 $\bar{1}$ 5) reflection for the control sample (b) and test sample (c) with the sample (S) and analyser (A) streak artifacts labelled. The AlGaN observed by XRD is due to GaN nucleation onto sapphire during commercial growth of the GaN template.

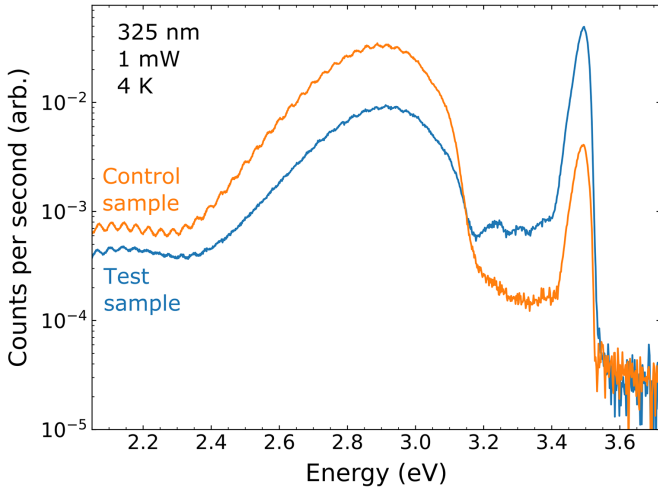


Figure 4. Low temperature photoluminescence (PL) of the control sample (orange) and test sample (blue). The defect luminescence band can be seen in both samples centered around 2.9 eV. The GaN and cation-ordered ZnGeN₂ band edge signals overlap at 3.5 eV. The peak at 2.15 eV is yellow band luminescence from the GaN template.

also obtained to analyze strain and defects. Lateral broadening around the GaN (1 0 $\bar{1}$ 5) is indicative of dislocations along the growth direction which act to decrease the lateral coherence length and increase broadening in reciprocal space [21]. Elongated features in Q_z represent the crystal truncation rod.

Low-temperature (4 K) PL was used to investigate the impact of unintentional impurities on optical properties (figure 4). The defect luminescence that can be seen in both samples as a broad feature centered around 2.9 eV originates from the ZnGeN₂ layer and overlaps a Zn:GaN impurity transition [21]. The 2.9 eV ZnGeN₂ peak was identified as a free-to-bound defect transition in a previous study where ZnGeN₂ was grown directly on AlN substrates without any GaN, noting that the same peak energy is also associated with a donor-acceptor pair in Zn:GaN [20, 29]. In a prior study, we used low temperature power dependent PL to differentiate the two overlapping luminescence signals [21]. A blue shift of the 2.9 eV peak with increasing power is characteristic of a donor-acceptor pair, while the absence of such shift is associated with a free-to-bound transition in ZnGeN₂ that may originate from either Zn_{Ge} antisites or Ga_{Ge} substitution. The control sample showed a clear blue-shift with increasing power; however, the test sample did not show any evidence of blue shifting over 3-orders of magnitude laser power (see SI figure 5). Thus, it appears that improvements to unintentional Ge and Ge incorporation have also reduced the unintentional Zn doping of GaN. The GaN band-edge signal is present in both samples and overlaps the band edge signal (3.5 eV) for cation-ordered ZnGeN₂. [30] The peak at 2.15 eV is yellow band luminescence from the GaN template.

APT and STEM-EDS were performed to investigate the interface abruptness and layer composition. Figure 5 shows comparative line scans from the APT reconstructions (directly through the middle of the reconstruction cone using a

33 nm diameter cylinder) for the control sample (a) and the test sample (c). The EDS line scans and elemental mapping can be found in SI figure 3. First, we note that for APT the detection sensitivity for cation:nitrogen ratio is proportional to the local electric field, leading to apparent variations in cation:N stoichiometry. For EDS, absorption of the low energy nitrogen x-ray lines can lead to underestimations of nitrogen content when using the Cliff-Lorimer method employed here [31]. Since we are concerned primarily with the cation distribution, we focus on those for the analyses. In both samples the five ZnGeN₂ layers can be clearly seen in both the APT and EDS plots.

APT shows that the control sample has unintentional incorporation of Ga and Ge outside of their expected layers. In the control sample, Ga (red trace) is found in the ZnGeN₂ layers at about 15%–25%, indicative of unintentional incorporation or alloying of Ga with the ZnGeN₂. Also visible by APT is Ge incorporation into the GaN layers. Small Ge peaks are visible within the GaN layers, about 4–5 nm into each GaN layer (dark blue peaks in the GaN layers; indicated with blue arrows). The Ge incorporation layer is corroborated through high-angle annular dark-field imaging (HAADF) approximately 5 nm above the preceding ZnGeN₂ layer. A small portion of the HAADF for each sample is shown in figure 5, aligned to the superlattice layers in the APT plot, also indicating Ge incorporation with blue arrows (STEM-EDS and full HAADF images in SI figures 3 and 4).

4. Discussion

Determining the source of unintentional Ga and Ge incorporation is essential to integrate ZnGeN₂ into III-N heterostructures and devices such as LEDs. We first hypothesized that stray Ga flux from the hot Ga cell at GaN growth temperature incorporated into the ZnGeN₂ layers in the control sample. Noting that the GaN growth rate is approximately 25x faster than ZnGeN₂ growth rate and that MBE shutters do not provide 100% flux isolation, escaping flux from the Ga cell behind the closed shutter could be enough to incorporate at alloy level compositions. To test this hypothesis, we grew the test sample with the Ga cell cooled to 700 °C, rather than keeping it at GaN growth temperature during the ZnGeN₂ layers, to reduce stray flux and unintentional incorporation. Such alloying is not unexpected—there have been prior reports of intentional formation of ZnGeN₂-GaN alloys both at low GaN concentrations and at the 50% ZnGeGa₂N₄ composition [16–18].

The Ge in the GaN layers was found to incorporate in a discrete layer about about 4–5 nm after the ZnGeN₂ layer, or after one MME GaN cycle, appearing like a delta-doped layer by HAADF (SI figure 4). We hypothesized that the Ge was riding upon the Ga metal adlayer during the metal-rich step of the first MME cycle, and then incorporating into the GaN during the nitrogen-rich step. A similar effect has been observed for Ge and other dopants and impurities which do not incorporate during metal-rich GaN growth [32, 33]. To stop this migration of Ge, the GaN layer growth method for the test sample was switched from three 10/10 s open/closed MME cycles to

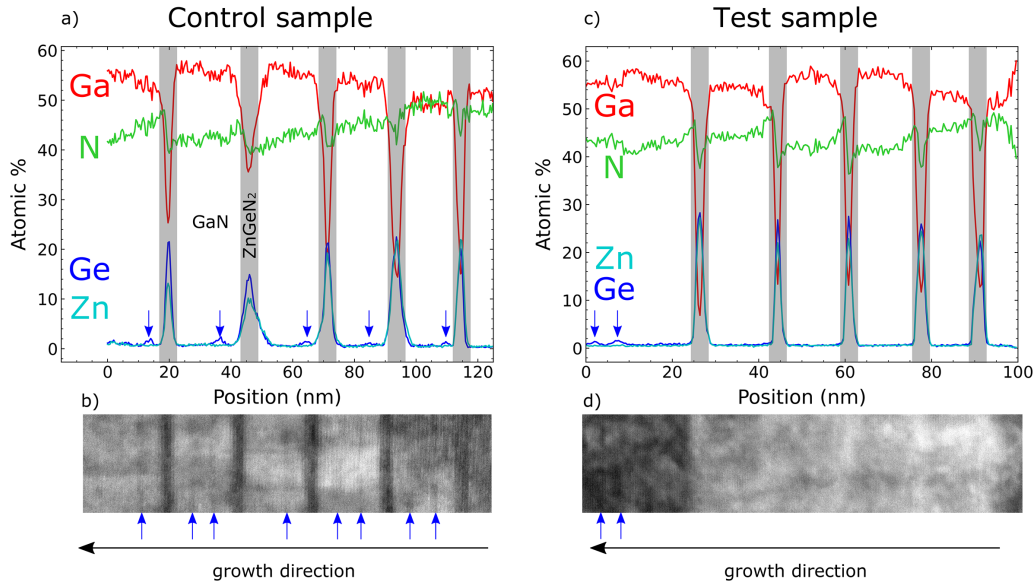


Figure 5. Atom probe tomography (APT) line profiles for the control (a) and test (c) samples. Plots show atomic % versus position within the superlattice region. Grey boxes indicate the ZnGeN₂ layers, with the GaN layers in between. Discrete spikes of Ge signal within the GaN layers are marked with blue arrows. The Ga signal does not drop to zero in the ZnGeN₂ layers. A portion of control (b) and test (d) sample HAADF rotated so superlattice layers align with the APT. Blue arrows also mark Ge incorporation.

one longer, 30/30 s open/closed MME cycle. This removed the opportunity for the residual Ge to incorporate into the GaN since there was no growth interrupt, while still growing the same GaN thickness.

Comparing the test and control samples, APT shows reduction in both Ge and Ga species outside of their respective layers, corroborating our hypotheses about incorporation in the control sample. As shown in figure 5(c), the Ga in the ZnGeN₂ layers is reduced from 15%–25% (control) to 8%–15% (test). The Ge peaks within the GaN layers have been completely eliminated to the resolution of the measurement. However, there are two Ge peaks visible in the GaN cap (marked with blue arrows in figures 5(c) and (d)) when the MME growth cycle reverted to 10 s open and 10 s closed, confirming that incorporation of excess Ge into GaN only occurs during nitrogen-rich steps. The presence of a second Ge peak corresponding to the second MME cycle is indicative of Ge exceeding the solid solubility limit in GaN, suggesting that Ge continually accumulates during repeated heterolayer growth and is incorporated until the excess germanium is completely consumed by nitrogen-rich growth steps. The source of Ge is unknown at this time but could be due to ZnGeN₂ decomposition at GaN growth temperatures. Alternative strategies, such as immediate low growth temperature, nitrogen-rich GaN nucleation or temperature ramping under a Zn-overpressure could be successful future strategies to reduce this decomposition.

Structural characterization shows improved structural uniformity correlated with the improved compositional uniformity. Symmetric XRD scans show increased material quality for the test growth, with three satellite peaks clearly observed compared to one satellite peak in the control sample.

Pendellösung fringes are clearer in the test sample indicating greater vertical coherence. RSMs of the test sample show that the GaN capping layer is less defective through decreased broadening in Q_x , indicating the test growth has fewer extended defects decreasing the lateral coherence length. Based on the width of the laterally broadened feature in Q_x the defect density in the five repeating unit superlattice film is not significantly different than the previously published double heterostructures, indicating that the additional superlattice interfaces do not significantly increase the Q_x broadening [20]. RHEED of both samples remains bright and streaky without a change in diffraction distance throughout the entire growth, confirming high-quality, commensurate growth of a 5-repeating superlattice layer structure, without significant loss in structural quality as the number of interfaces is increased (SI figure 2(b)).

PL (figure 4) found improvement in optical properties in the test sample with reduced unintentional incorporation of Ge and Ga. Three longitudinal-optical (LO) phonon replicas are visible in the test sample (blue), but not the control sample (orange), indicating that the crystalline and optical quality of the GaN cap is significantly improved. In contrast to previously published work, the LO phonon replicas are associated with GaN free exciton emission rather than a Zn:GaN acceptor bound exciton [20]. The increased band edge luminescence in the test sample compared to the control sample suggests some combination of decreased parasitic absorption by the ZnGeN₂ layer, increased luminescence from the GaN cap, and potentially band edge luminescence from ZnGeN₂. Decreased intensity of the 2.9 eV defect band in the test sample corroborates fewer defects and decreased parasitic absorption in the ZnGeN₂ layer. Overall,

the improvements in structural quality and superlattice layer abruptness result in measurable improvements to the PL spectra through increasing band edge signal and decreased defect luminescence.

In conclusion, we have demonstrated ZnGeN₂/GaN superlattices grown by MBE, methods to control unintentional incorporation in each heterolayer, and resulting improvements to the luminescence response. Structural and compositional analysis of both control and test samples reveal stray Ga flux and Ge incorporation during the nitrogen-rich MME stage to be the sources of unintentional impurity incorporation in ZnGeN₂ and GaN layers respectively. By controlling for these factors, the Ga concentration in ZnGeN₂ layers was reduced by 50%–60% compared to the control sample and Ge in the GaN layers was reduced to below the detection limit. PL confirms the impact of impurities on optical properties with the test sample having reduced defect signal and visible phonon replicas. The demonstration of superlattices with abrupt interfaces and control of unintentional impurities are important steps towards enabling hybrid III-N/II-IV-N₂ optoelectronic devices and establishes a path forwards towards highly efficient cm-LEDs.

Data availability statement

All data that support the findings of this study are included within the article (and any supplementary files).

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Conflicts of Interest

The authors have no conflicts of interest to declare.

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